

**Amendments to the Claims**

This listing of Claims will replace all prior versions and listings of Claims in the application.

**Listing of Claims**

1. (Currently amended) A method for packaging a semiconductor device, comprising the steps of:

- (a) forming a plurality of grooves on an upper surface of a substrate;
- (b) attaching a heat sink on the upper surface of the substrate;
- (c) attaching a chip to the substrate by using an adhesive;
- (d) wire-bonding the substrate and the chip; and
- (e) encapsulating and sealing the substrate and the chip by using an epoxy molding compound,

wherein the epoxy molding compound is attached the substrate through the plurality of grooves.

2. (Original) The method of claim 1, wherein at least one surface of the heat sink is exposed to the atmosphere.